NEWS RELEASE

FOR IMMEDIATE RELEASE

Mi Material Reports Robust 9M2026 Performance, Maintains Positive Growth Outlook

- *Revenue reached US$91.5 million in 9M2026, supported by higher sales volumes and selling prices, with 3Q2026 revenue growing 15.6% quarter-on-quarter*
- *Maintained strong profitability, with gross profit margin of 46.6% and adjusted profit after tax of US$25.7 million in 9M2026, reflecting continued earnings growth from 1H2026*
- *Positive outlook for 4Q2026, traditionally the Group's seasonally strongest quarter, supported by sustained demand for our patented alloy solder spheres*

SINGAPORE, 29 October 2026 – Mi Material Holding Limited ("**Mi Material**" or the "**Company**", and together with its subsidiaries, the "**Group**"), a leading global supplier of precision solder spheres used in advanced semiconductor packaging, today announced its business update for the nine months ended 30 September 2026 ("**9M2026**"), delivering strong revenue growth and improved profitability on the back of sustained demand for its semiconductor packaging materials.

The Group recorded revenue of US$91.5 million in 9M2026, surpassing its revenue of US$65.3 million for the full year ended 31 December 2025 ("**FY2025**"). Revenue growth was principally attributable to increases in both sales volume and average selling prices. This was underpinned by continued strong demand for the Group's proprietary patented alloy solder spheres from customers in the high-performance computing ("HPC") and memory segments, as well as the mobility and wearables segment.

Continued Growth Momentum in 3Q2026

Building on its strong performance in the first half of FY2026, Mi Material recorded revenue of US$37.8 million for the three months ended 30 September 2026 ("**3Q2026**"), representing a 15.6% increase from US$32.7 million in the preceding quarter ("**2Q2026**"). The sequential growth was primarily driven by higher sales volumes, in line with seasonal trends, reflecting sustained customer demand for the Group's patented alloy solder spheres.

Gross profit for 9M2026 amounted to US$42.6 million, while gross profit margin improved to 46.6%, from 45.8% in the six months ended 30 June 2026 ("**1H2026**"). Gross profit margin for 3Q2026 was 47.6%, broadly stable compared with 48.0% in 2Q2026. The improvement in gross profit margin was supported by a favourable shift in product mix towards higher-margin proprietary alloys, alongside higher sales volumes and selling prices.

Adjusted profit after tax margin for 9M2026 stood at 28.1%, compared with 26.6% in 1H2026, reflecting the Group's ability to translate revenue growth into stronger earnings.

Positive Outlook Supported by Semiconductor Industry Trends

Looking ahead, Mi Material remains optimistic about its growth prospects for the remainder of FY2026, supported by favourable industry trends and sustained demand for advanced semiconductor packaging materials. Growth is expected to be driven by continued momentum in the HPC and memory segments, alongside strong demand in the mobility and wearables segment, supported by miniaturisation and higher input/output density in premium devices.

These trends, together with Mi Material's established materials expertise and portfolio of specialty alloys, are expected to support opportunities for new programme wins and deepen the Group's relationships with its global customer base.

The fourth quarter has historically been the Group's seasonally strongest quarter. Against this backdrop, Mi Material expects positive revenue momentum to continue in 4Q2026, supported by sustained demand across key end markets.

Mr Kevin Tan, Chief Executive Officer of Mi Material, said: “Our performance in the first nine months of 2026 reflects sustained demand for our precision semiconductor packaging materials and the strength of our customer relationships. We are encouraged by the continued growth momentum across the various end segments of our business

Following our successful listing on the SGX Mainboard, we remain focused on executing our growth plans and building on the capabilities we have developed over the years. As we enter what is traditionally our strongest quarter, we are optimistic about the opportunities ahead. With our strong financial position and established materials expertise, we are well-positioned to expand our manufacturing capacity, advance our R&D initiatives and create long-term value for our shareholders.”

– END –

About Mi Material Holding Limited

Mi Material Holding Limited ("Mi Material") is a leading manufacturer of semiconductor advanced packaging materials, specialising in the design, development, manufacturing and commercialisation of precision solder spheres and related interconnect solutions used in advanced semiconductor packaging applications. Headquartered in Singapore, the Group serves leading semiconductor foundries, integrated device manufacturers and outsourced semiconductor assembly and test providers globally.

The Group's products support key end markets including artificial intelligence (AI), high-performance computing (HPC), memory, mobile devices and automotive electronics.

For more information, visit *www.mi-material.com*

Media Enquiries
Sherilyn Yang, Associate Director
H/Advisors
MiMaterial-Singapore@h-advisors.global